## **General Description**

DA9122 is a power management unit (PMU) suitable for supplying CPUs, GPUs, DDR memory rails in single in-line pin package (SIPP) modules, smartphones, tablets, and other handheld applications.

DA9122 integrates two single-phase buck converters, each phase requiring a small external 0.10  $\mu$ H inductor. Each buck is capable of delivering up to 5 A output current at a 0.3 V to 1.9 V output voltage range. The 2.5 V to 5.5 V input voltage range is suitable for a wide variety of low-voltage systems, including, but not limited to, all Li-Ion battery supplied applications.

With remote sensing, the DA9122 guarantees the highest accuracy and supports multiple PCB routing scenarios without loss of performance.

The pass devices are fully integrated, so no external FETs or Schottky diodes are needed.

A programmable soft start-up can be enabled, which limits the inrush current from the input node and secures a slope-controlled rail activation.

The dynamic voltage control (DVC) supports adaptive adjustment of the supply voltage dependent on the processor load, via either a direct register write using the communication interface (I<sup>2</sup>C-compatible) or with a programmable input pin.

A configurable GPI allows multiple I<sup>2</sup>C address selection for multiple instances of DA9122 in the same application.

DA9122 has integrated over-temperature and over-current-protection for increased system reliability, without the need for external sensing components.

## **Key Features**

- 2.5 V to 5.5 V input voltage
- 0.3 V to 1.9 V output voltage
- 4 MHz nominal switching frequency
- ±1 % accuracy (static)
- ±5 % accuracy (dynamic)
- I<sup>2</sup>C-compatible interface (FM+)
- Programmable GPIOs
- Programmable soft-start

## **Applications**

- SIPP modules (SoC, DRAM)
- Smartphones
- Tablet PCs
- Infotainment

- Voltage, current, and temperature supervision
- -40 °C to +85 °C ambient temperature range
- Package: 24WLCSP 2.48 mm x 1.68 mm (0.4 mm pitch)
- Ultrabooks<sup>™</sup>
- Wi-Fi -Modules
- Game Consoles

# **System Diagrams**

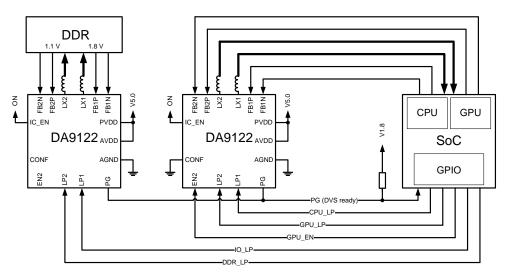


Figure 1: Typical Application Diagram (Port Control)

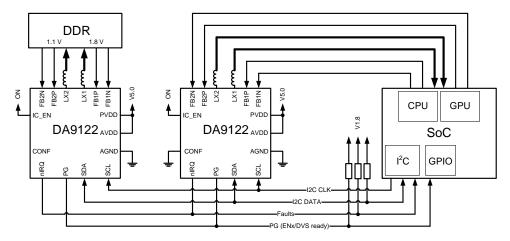


Figure 2: Typical Application Diagram (I<sup>2</sup>C Control)

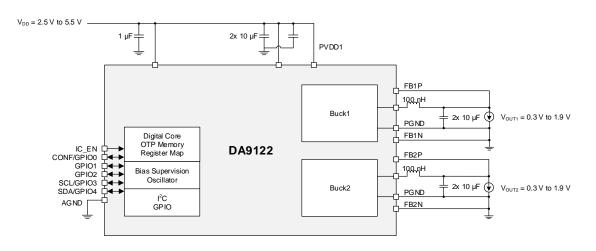


Figure 3: Simplified Schematic Diagram

**Datasheet** 



## High-Performance Dual-Channel DC-DC Converter

## **Contents**

Ge	neral l	Descriptio	on	1
Ke	y Feat	ures		1
Ар	plicati	ons		1
Sv	stem [	Diagrams		2
1		•	finitions	
2				
2			s	
ა	3.1		<b>s</b> Maximum Ratings	
	3.1 3.2		ended Operating Conditions	
	3.2 3.3		Characteristics	
	5.5	3.3.1	Thermal Ratings	
		3.3.2	Power Dissipation	
	3.4		aracteristics	
	3.5		aracteristics	
	3.6		ance and Supervision Characteristics	
	3.7		D Characteristics	
	3.8	•	haracteristics	
	3.9	•	Performance	
4			scription	
-	4.1		Buck Converter	
	7.1	4.1.1	Switching Frequency	
		4.1.2	Operation Modes and Phase Selection	
		4.1.3	Output Voltage Selection	
		4.1.4	Soft Start-Up and Shutdown	
		4.1.5	Current Limit	
		4.1.6	Thermal Protection	
	4.2	-	Circuits	
		4.2.1	IC_EN/Chip Enable/Disable	
		4.2.2	nIRQ/Interrupt	
		4.2.3	GPIO	
	4.3	Operating	g Modes	
		4.3.1	ON	
		4.3.2	OFF	
	4.4	I <sup>2</sup> C Comr	munication	
		4.4.1	I <sup>2</sup> C Protocol	
5	Regis	ster Defin	itions	
	5.1	Register	Мар	
		5.1.1	System	
		5.1.2	Buck1	
		5.1.3	Buck2	
		5.1.4	Serialization	
6	Packa	age Inforr	nation	55
	6.1	Package	Outlines	55
Dat	tashee	et	Revision 2.3	24-Apr-2023

CFR0011-120-00

	6.2	Moisture Sensitivity Level	. 56
	6.3	WLCSP Handling	. 56
	6.4	Soldering Information	. 56
7	Orde	ring Information	. 57
8	Appli	cation Information	. 57
	8.1	Capacitor Selection	. 57
	8.2	Inductor Selection	. 58



# High-Performance Dual-Channel DC-DC Converter

# **1** Terms and Definitions

ATE	Automated test equipment
CPU	Central processing unit
DDR	Dual data rate
DVC	Dynamic voltage control
FET	Field effect transistor
FM+	Fast mode plus
GBD	Guaranteed by design
GBQ	Guaranteed by qualification
GBSPC	Guaranteed by statistical process characterization
GPI	General purpose input
GPIO	General purpose input/output
GPU	Graphics processing unit
IC	Integrated circuit
HW	Hardware
Li-Ion	Lithium-ion
OTP	One time programmable
PCB	Printed circuit board
PRS	Product requirements specification
SCL	Serial clock
SDA	Serial data
SIPP	Single in-line pin package
SW	Software



# High-Performance Dual-Channel DC-DC Converter

## 2 Pinout

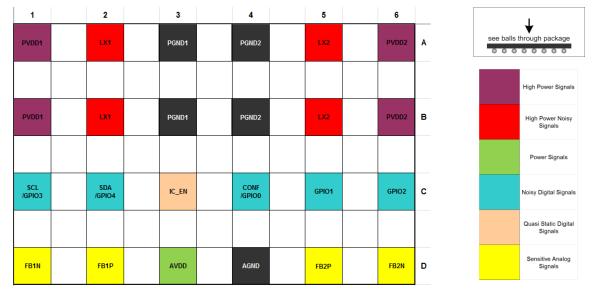


Figure 4: DA9122 Pinout Diagram (Top View)

#### **Table 1: Pin Description**

Pin No.	Pin Name	Type (Table 2)	Drive (mA)	Reset State	Description
A1, B1	PVDD1	PWR	5000		Supply voltage for Buck1 power stage, decouple with 10 $\mu F$ and connect to same source as AVDD
A2, B2	LX1	AIO	5000		Switch node of Buck1, connect a 100 nH inductor between LX1 and output capacitor
A3, B3	PGND1	GND	5000		Buck1 power stage VSS rail
A4, B4	PGND2	GND	5000		Buck2 power stage VSS rail
A5, B5	LX2	AIO	5000		Switch node of Buck2, connect a 100 nH inductor between LX2 and output capacitor
A6, B6	PVDD2	PWR	5000		Supply voltage for Buck2 power stage, decouple with 10 $\mu F$ and connect to same source as AVDD
C1	SCL/GPIO3	DIO/DO	15		I <sup>2</sup> C clock or general purpose output
C2	SDA/GPIO4	DIO/DO	15		I <sup>2</sup> C data or general purpose output
C3	IC_EN	AI	10		Powers up SW control interface and auxiliary circuitry (for example, bandgap, oscillator, and references).
C4	CONF/GPIO0	AI/DIO	10		Chip configuration or general purpose I/O
C5	GPIO1	DIO	10		General purpose I/O
C6	GPIO2	DIO	10		General purpose I/O
D1	FB1N	AI	10		Buck1 negative node of differential voltage feedback, connect to VSS at point of load
D2	FB1P	AI	10		Buck1 positive node of differential voltage feedback, connect to $V_{OUT1}$ at point of load

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Datasheet
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**Revision 2.3** 



## High-Performance Dual-Channel DC-DC Converter

Pin No.	Pin Name	Type (Table 2)	Drive (mA)	Reset State	Description
D3	AVDD	PWR	10		Supply rail for analog control circuitry, decouple with 1 $\mu F$ and connect to same source as PVDD
D4	AGND	GND	10		Analog control and auxiliary circuitry VSS
D5	FB2P	AI	10		Buck2 positive node of differential voltage feedback, connect to $V_{OUT2}$ at point of load
D6	FB2N	AI	10		Buck2 negative node of differential voltage feedback, connect to VSS at point of load

### Table 2: Pin Type Definition

Pin Type	Description	Pin Type	Description
DI	Digital input	AI	Analog input
DO	Digital output	AO	Analog output
DIO	Digital input/output	AIO	Analog input/output
PWR	Power	GND	Ground

## **3** Characteristics

### 3.1 Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

#### Table 3: Absolute Maximum Ratings

Parameter	Description	Conditions	Min	Мах	Unit
T <sub>STG</sub>	Storage temperature		-65	150	°C
TJ	Junction temperature		-40	150	°C
Vsys	System supply voltage		-0.3	6.0	V
VPIN	Voltage on pins		-0.3	6.0	V

### 3.2 Recommended Operating Conditions

#### **Table 4: Recommended Operating Conditions**

Parameter	Description	Conditions (Note 1)	Min	Тур	Мах	Unit
Vsys	System supply voltage		2.5		5.5	V
Vpin	Voltage on pins		-0.3		V <sub>SYS</sub> + 0.3	V
TJ	Junction temperature		-40		125	°C
TA	Ambient temperature		-40		85	°C

**Note 1** Within the specified limits, a lifetime of 10 years is guaranteed. If operating outside of these recommended conditions, please consult with Renesas Electronics.



### High-Performance Dual-Channel DC-DC Converter

### 3.3 Thermal Characteristics

### **3.3.1 Thermal Ratings**

#### Table 5: Package Ratings

Parameter	Description	Conditions	Min	Тур	Max	Unit
Αμθ	Package thermal resistance Note 1			32.7		°C/W

Note 1 Obtained from package thermal simulation, 2S2P4L board (JEDEC), influenced by PCB technology and layout.

#### 3.3.2 **Power Dissipation**

#### **Table 6: Power Dissipation**

Parameter	Description	Conditions	Min	Тур	Max	Unit
PD	Power dissipation	Derating factor above $T_A = 70^{\circ}C$ : 30.6 mW/°C (1/ $\theta_{JA}$ )		2140		mW

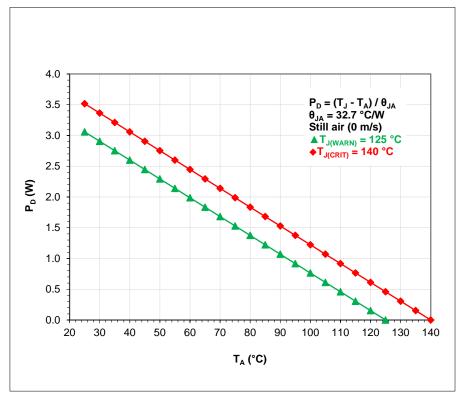


Figure 5: 24WLCSP Power Derating Curve

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### 3.4 ESD Characteristics

#### **Table 7: ESD Characteristics**

Parameter	Description	Conditions	Min	Тур	Max	Unit
$V_{\text{ESD}_{\text{HBM}}}$	ESD protection, human body model (HBM)				2	kV



## High-Performance Dual-Channel DC-DC Converter

### 3.5 Buck Characteristics

Unless otherwise noted, the following is valid for  $T_J$  = -40 °C to +125 °C,  $V_{SYS}$  = 2.5 V to 5.5 V

e, per Itage and ient	V <sub>IN</sub> = V <sub>SYS</sub>	2.5			
Itage and	VIN = VSYS	2.5			
Itage and				5.5	V
		-40 %	2 x 10	+30 %	μF
eries se	f > 100 kHz		2		mΩ
nd		-50 %	0.1	+20 %	μH
nce			30	50	mΩ
0 mV	$I_{OUT} = 0 \text{ mA to } I_{MAX}$ $V_{IN} = 2.5 \text{ V to } 5.5 \text{ V}$	0.3		1.57	V
0 mV	$\begin{split} &I_{OUT}=0 \text{ mA to }I_{MAX} \\ &V_{IN}=3.0 \text{ V to } 5.5 \text{ V} \end{split}$	0.3		1.9	V
ammable	CHx_ILIM = 1010	-20 %	8	+20 %	A
	V <sub>OUT</sub> ≥ 1 V	-1		1	%
	Vout < 1 V	-10		10	mV
e	Referred to Vout	-80	-50	-20	mV
	Referred to Vout	-160	-130	-100	mV
hreshold	Referred to VOUT	100	150	200	mV
onse	V <sub>IN</sub> = 3 V to 3.6 V I <sub>OUT</sub> = 0.5 * I <sub>MAX</sub> dt = 10 µs		15		mV
y, post-			4		MHz
	phase, nd dence ince 0 mV 0 mV ammable uracy, and load uracy, and load e e hreshold onse y, post-	Ind denceInce0 mVIout = 0 mA to IMAX VIN = 2.5 V to 5.5 V0 mVIout = 0 mA to IMAX VIN = 3.0 V to 5.5 V0 mVIout = 0 mA to IMAX VIN = 3.0 V to 5.5 VammableCHx_ILIM = 1010uracy, and loadVout $\geq$ 1 Vuracy, and loadVout $\geq$ 1 VeReferred to VouteReferred to VouteReferred to VouthresholdReferred to VoutbrieseVIN = 3 V to 3.6 V Iout = 0.5 * IMAX dt = 10 µs	Ind dence-50 %Ince-50 %0 mVIout = 0 mA to IMAX VIN = 2.5 V to 5.5 V0.30 mVIout = 0 mA to IMAX VIN = 3.0 V to 5.5 V0.30 mVIout = 0 mA to IMAX VIN = 3.0 V to 5.5 V0.3ammableCHx_ILIM = 1010-20 %uracy, and loadVout ≥ 1 V-1uracy, and loadVout > 1 V-10eReferred to Vout-80eReferred to Vout-160hresholdReferred to Vout100onseVIN = 3 V to 3.6 V Iout = 0.5 * IMAX dt = 10 µs-10 µs	Ind dence-50 %0.1Ince300 mV $l_{OUT} = 0$ mA to $l_{MAX}$ $V_{IN} = 2.5 V$ to $5.5 V$ 0.30 mV $l_{OUT} = 0$ mA to $l_{MAX}$ $V_{IN} = 3.0 V$ to $5.5 V$ 0.3ammableCHx_ILIM = 1010-20 %uracy, and loadVout $\geq 1 V$ -1uracy, and loadVout $< 1 V$ -10eReferred to $V_{OUT}$ -80-50eReferred to $V_{OUT}$ 100150hresholdReferred to $V_{OUT}$ 100150onse $V_{IN} = 3 V$ to $3.6 V$ $lout = 10 \mu s$ 15	Ind dence       -50 %       0.1       +20 %         Ince       30       50         Ince       30       50         0 mV $I_{OUT} = 0$ mA to $I_{MAX}$ $V_{IN} = 2.5 V to 5.5 V       0.3       1.57         0 mV       I_{OUT} = 0 mA to I_{MAX}V_{IN} = 3.0 V to 5.5 V       0.3       1.9         ammable       CHx_ILIM = 1010       -20 %       8       +20 %         uracy,and load       Vout > 1 V       -11       1       1         uracy,and load       Vout < 1 V$

#### **Table 8: Buck Electrical Characteristics**

Datasheet



Parameter	Description	Conditions	Min	Тур	Max	Unit
ton_min	Minimum turn-on pulse 0 % duty is also supported			20		ns
tbuck_en	Turn-on time	CHx_EN = high			20	μs
R <sub>PD</sub>	Output pull-down resistance for each phase at the LX node, see CHx_PD_DIS	V <sub>IN</sub> = 3.7 V, V <sub>OUT</sub> = 0.5 V	100	150	200	Ω
Ron_pmos	On resistance of switching PMOS, per phase	V <sub>IN</sub> = 3.7 V		36		mΩ
Ron_nmos	On resistance of switching NMOS, per phase	V <sub>IN</sub> = 3.7 V		17		mΩ
AUTO Mode						
Vout_tr_ld_1 ph	Load transient response	1-phase V <sub>OUT</sub> = 1 V I <sub>OUT</sub> = 0 A to 5 A dl/dt = 10 A/μs		±5		%
PFM Mode						
IQ_PFM_1PH	Quiescent current in PFM	$\begin{array}{l} \mbox{1-phase} \\ \mbox{V}_{\rm IN} = 3.7 \ \mbox{V} \\ \mbox{No load} \\ \mbox{No switching} \end{array}$		88		μΑ

**Note 1** ton > 40 ns

### 3.6 **Performance and Supervision Characteristics**

#### **Table 9: Electrical Characteristics**

Parameter	Description	Conditions	Min	Тур	Max	Unit			
Electrical Performance									
VTHR_POR	Power-on-reset threshold	Threshold for AVDD falling		2.1	2.25	V			
Vthr_por_hy s	Power-on-reset hysteresis			200		mV			
Twarn	Thermal warning temperature threshold		115	125	135	°C			
T <sub>CRIT</sub>	Thermal shutdown temperature threshold		130	140	150	°C			
IIN_OFF	Supply current	OFF state T <sub>A</sub> = 27 °C IC_EN = 0		0.1	1	μA			





Parameter	Description	Conditions	Min	Тур	Max	Unit
lin_on	Supply current	ON state T <sub>A</sub> = 27 °C IC_EN = 1 Buck off	5	10	20	μA

## 3.7 Digital I/O Characteristics

#### Table 10: Digital I/O Electrical Characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit			
Electrical Performance									
VIH_EN	Input high voltage, IC enable		1.2		AVDD	V			
VIL_EN	Input low voltage, IC enable				0.4	V			
tic_en	IC enable time				1000	μs			
Vih_gpio_scl _sda	Input high voltage GPIO, SCL, SDA		1.2		AVDD	V			
Vil_gpio_scl_ sda	Input low voltage GPIO, SCL, SDA				0.4	V			
Voh_gpio	Output high voltage GPIO	Push-pull mode lout = 1 mA	0.8*AV DD		AVDD	V			
Vol_gpio	Output low voltage GPIO	Push-pull mode I <sub>OUT</sub> = 1 mA			0.2*AV DD	V			
Vol_sda	Output low voltage SDA	Ιουτ = 3 mA		0.24		V			
R <sub>PD</sub>	GPIO pull-down resistor		2	10	120	kΩ			
Rpu	GPIO pull-up resistor		2	10	120	kΩ			



## High-Performance Dual-Channel DC-DC Converter

## 3.8 Timing Characteristics

#### Table 11: I2C Electrical Characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit		
Electrical Performance								
tBUS	Bus free time between a STOP and START condition		0.5			μs		
CBUS	Bus line capacitive load				150	pF		
fscL	SCL clock frequency		20 Note 1		1000	kHz		
tLO_SCL	SCL low time		0.5			μs		
tHI_SCL	SCL high time		0.26			μs		
trise	SCL and SDA rise time	Requirement for input			1000	ns		
tFALL	SCL and SDA fall time	Requirement for input			300	ns		
tsetup_start	Start condition setup time		0.26			μs		
thold_start	Start condition hold time		0.26			μs		
tSETUP_STOP	Stop condition setup time		0.26			μs		
t <sub>DATA</sub>	Data valid time				0.45	μs		
t <sub>data_ack</sub>	Data valid acknowledge time				0.45	μs		
tsetup_data	Data setup time		50			ns		
thold_data	Data hold time		0			ns		

Note 1 Minimum clock frequency is limited to 20 kHz if I2C\_TIMEOUT is enabled

**Datasheet** 

### **3.9 Typical Performance**

Unless otherwise noted,  $V_{IN} = 3.7 \text{ V}$ ,  $V_{OUT} = 1.0 \text{ V}$ ,  $T_A = 25 \text{ °C}$ , 2.0 mm x 1.6 mm 0.1 µH output inductor (DCR = typ. 11.5 m $\Omega$ ) and 2 x 10 µF output capacitors per-channel.

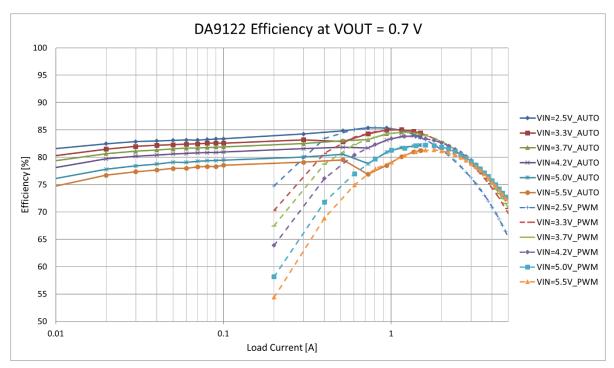
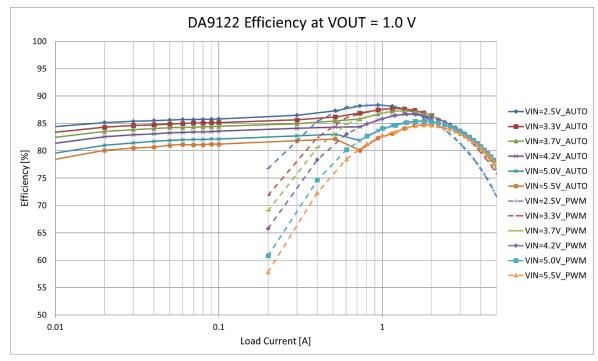
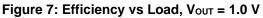


Figure 6: Efficiency vs Load, Vout = 0.7 V





Datasheet	Revision 2.3

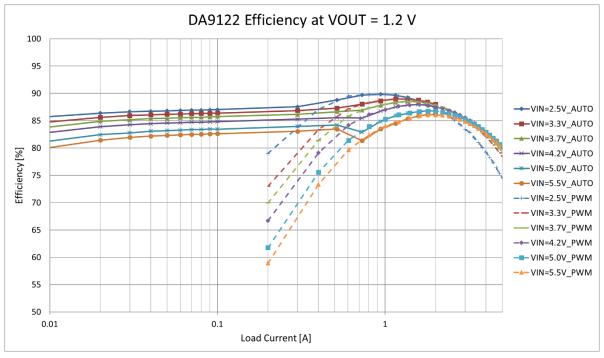


Figure 8: Efficiency vs Load, Vout = 1.2 V

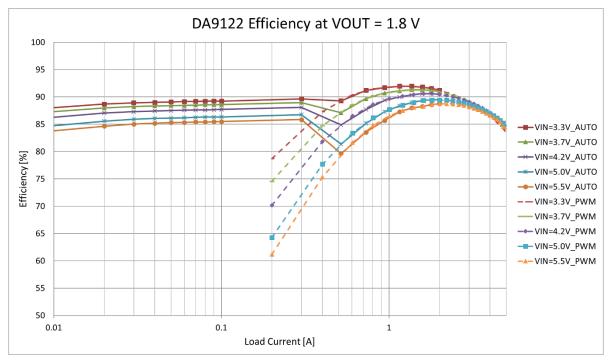


Figure 9: Efficiency vs Load, Vout = 1.8 V

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Da	las	ne	eι



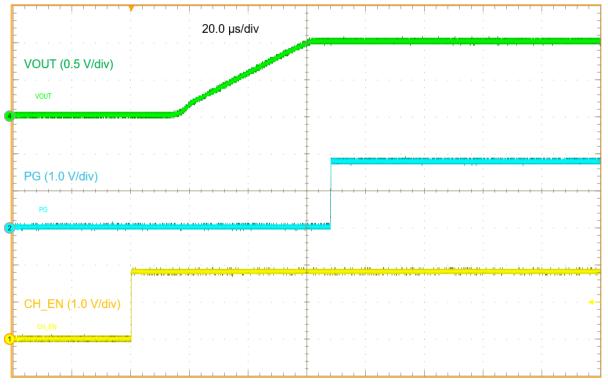


Figure 10: Buck SoftStart-up at 20 mV/µs Slew Rate

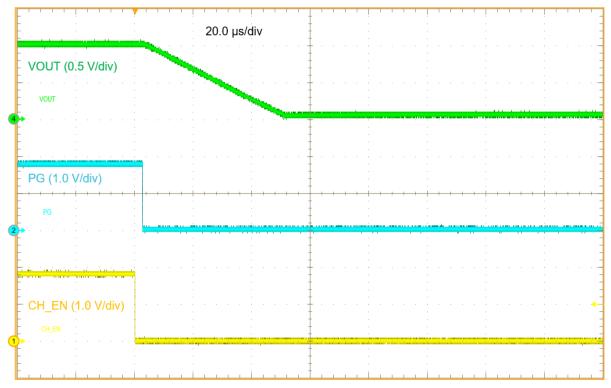


Figure 11: Buck Active Shutdown at 20 mV/µs Slew Rate

n.	-4	-	<b>_</b> L		et
	- 11	а	51	1e	eт
_	-	-	-		

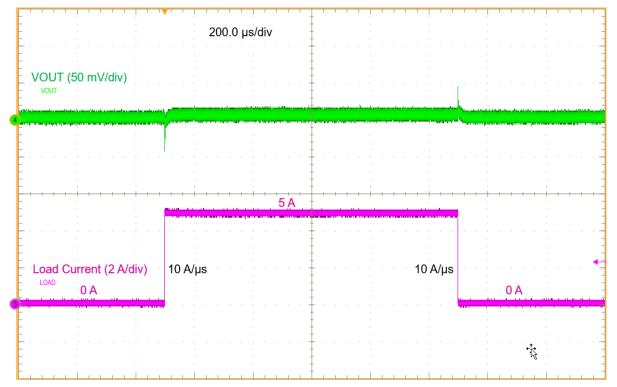


Figure 12: Buck Load Transient Response in Forced PWM Mode, 0 A to 5 A at 10 A/ $\!\mu s$ 

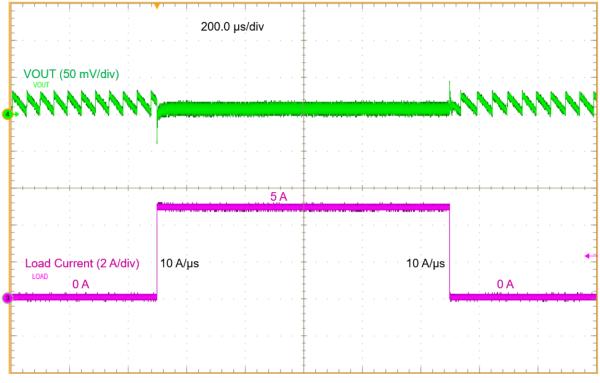


Figure 13: Buck Load Transient Response in AUTO Mode, 0 A to 5 A at 10 A/µs

**Datasheet** 

## 4 Functional Description

### 4.1 DC-DC Buck Converter

DA9122 contains two buck converters, Buck1 and Buck2, each capable of delivering up to 5 A output current at a 0.3 V to 1.9 V output voltage range.

Buck1 and Buck2 have two voltage registers each. One defines the normal output voltage, while the other offers an alternative retention voltage. In this way, different application power modes can easily be supported. The voltage selection can be operated either via GPI or via control interface to guarantee the maximum flexibility according to the specific host processor status in the application.

When a buck is enabled, its output voltage is monitored and a power good signal indicates that the buck output voltage has reached a level higher than the  $V_{THR_PG_RISE}$  threshold. The power good status is lost when the voltage drops below  $V_{THR_PG_DWN}$  or increases above  $V_{THR_HV}$ . For each of the buck converters the status of the power good indicator can be read back via I<sup>2</sup>C from the PG1 and PG2 status bits. It can be also individually assigned to any of the GPIOs by setting the GPIO mode registers to either PG1 or PG2 output.

The buck converters are capable of supporting DVC transitions that occur:

- When the active and selected A- or B-voltage is updated to a new target value.
- When the voltage selection is changed from the A- to B-voltage (or B- to A-voltage) using CH<x>\_VSEL.

The DVC controller operates in pulse width modulation (PWM) mode with synchronous rectification.

The slew rate of the DVC transition is individually programmed for each buck converter at 10 mV per 8 µs, 4 µs, 2 µs, 1 µs, or 0.5 µs in register bits CH1\_SR\_DVC and CH2\_SR\_DVC.

A pull-down resistor (typically 150  $\Omega$ ) for each phase is always activated unless it is disabled by setting register bits CH<x>\_PD\_DIS to 1.

#### 4.1.1 Switching Frequency

The buck switching frequency can be tuned using register bit OSC\_TUNE. The internal 8 MHz oscillator frequency is tuned in  $\pm 160$  kHz steps. This impacts the buck converter frequency in steps of 80 kHz and helps to mitigate possible disturbances to other high frequency systems in the application.

#### 4.1.2 Operation Modes and Phase Selection

The buck converters can operate in PWM and PFM modes. The operating mode is selected using register bits CH1\_<A or B>\_MODE and CH2\_<A or B>\_MODE.

If the automatic operation mode is selected on CH1\_<A or B>\_MODE or CH2\_<A or B>\_MODE, the buck converters automatically change between synchronous PWM mode and PFM depending on the load current. This improves the efficiency across the whole range of output load currents.

#### 4.1.3 Output Voltage Selection

The switching converter can be configured using the I<sup>2</sup>C interface.

For each buck converter two output voltages can be pre-configured in registers CH<x>\_<A or B>\_VOUT. The output voltage can be selected by either toggling register bit CH<x>\_VSEL or by reprogramming the selected voltage control register. Both changes will result in ramped voltage transitions. After being enabled, the buck converter will, by default, use the register settings in CH<x>\_A\_VOUT unless the output voltage selection is configured via the GPI port.

Registers CH<1 and 2>\_VMAX limit the output voltage that can be set for each of the respective buck converters.

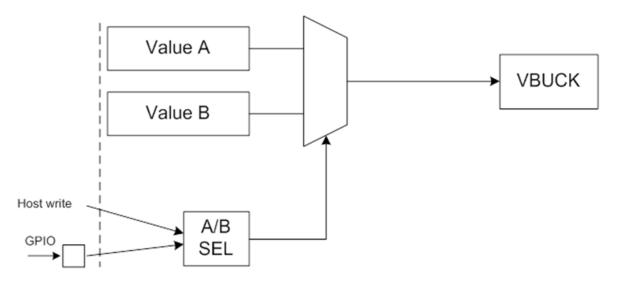


Figure 14: Buck Output Voltage Control Concept

#### 4.1.4 Soft Start-Up and Shutdown

To limit in-rush current from VSYS, the buck converters can perform a soft-start after being enabled. The start-up behavior is a compromise between acceptable inrush current from the battery and turnon time. Individual ramp times can be configured for each buck converter in registers CH<1 and 2>\_SR\_STARTUP respectively. Rates higher than 20 mV/µs may produce overshoot during the start-up phase, so they should be considered carefully.

A ramped power down can be selected in register bits CH<1 and 2>\_SR\_SHDN. When no ramp is selected (immediate power down), the output node will be discharged only by the pull-down resistor, if enabled in registers CH<1 and 2>\_PD\_DIS.

#### 4.1.5 Current Limit

The integrated current limit protects the power stages and external coil from excessive current. The buck current limit should be configured to at least 40 % higher than the required maximum output current.

When the current limit is reached, each buck converter generates an event and an interrupt to the host processor unless the interrupt has been masked using register M\_OC<x> in SYS\_MASK\_1. Register bits OC\_DVC\_MASK is used to mask over-current events during DVC transitions.

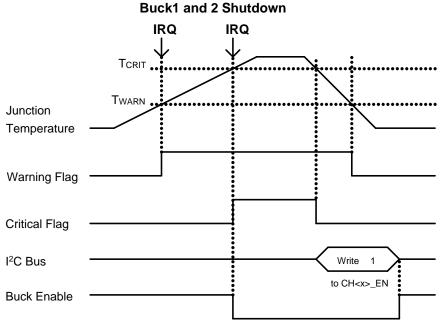
#### 4.1.6 Thermal Protection

DA9122 is protected from internal overheating by thermal shutdown.

There are two kinds of flags concerning thermal protection, thermal warning and thermal critical. The warning flag is asserted when  $T_J > T_{WARN}$  and the critical flag is asserted when  $T_J > T_{CRIT}$ . When the critical flag is asserted, Buck1 and 2 are shut down immediately.

Category	Register name	Description
Statua	TEMP_WARN	Asserted as long as the thermal warning threshold is reached
Status	TEMP_CRIT	Asserted as long as the thermal shutdown threshold is reached
	E_TEMP_WARN	TEMP_WARN caused event
IRQ event	E_TEMP_CRIT	TEMP_CRIT caused event
	M_TEMP_WARN	TEMP_WARN event IRQ mask
IRQ mask	M_TEMP_CRIT	TEMP_CRIT event IRQ mask
	M_VR_HOT	TEMP_WARN status IRQ mask

#### **Table 12: Thermal Protection Control Registers**





### 4.2 Internal Circuits

### 4.2.1 IC\_EN/Chip Enable/Disable

IC\_EN is chip enable/disable control input. When IC\_EN = 0, all blocks except for low  $I_Q$  POR are powered-down and buck output is pulled-down.

#### 4.2.2 nIRQ/Interrupt

The interrupt triggers events. Trigger conditions and control registers for each interrupt event are listed in Table 13.

Some of these events are categorized as fault events and affect device operation (for example, buck disable), see Section 4.1.6.

Name	Polarity (Note 1)	Trigger	IRQ Status Register	IRQ Mask Register	Deglitch Period
Thermal warning (event)	N	TJ rising above Twarn	E_TEMP_WARN	M_TEMP_WARN	0 s
Thermal critical (event)	N	$T_{\rm J}$ rising above $T_{\rm CRIT}$	E_TEMP_CRIT	M_TEMP_CRIT	0 s
System good (event)	Р		E_SG	M_SG	0 s
Buck1 power- good (event)	Ρ	Buck1 V <sub>OUT</sub> is in power- good voltage range (not under- or over-voltage)	E_PG1	M_PG1	0 s
Buck2 power- good (event)	Ρ	Buck2 V <sub>OUT</sub> is in power- good voltage range (not under- or over-voltage)	E_PG2	M_PG2	0 s
Buck1 over- voltage (event)	N	Buck1 V <sub>OUT</sub> rising above over-voltage threshold (target voltage + 150 mV)	E_OV1	M_OV1	Rise:8 µs Fall:8 µs
Buck2 over- voltage (event)	N	Buck2 V <sub>OUT</sub> rising above over-voltage threshold (target voltage + 150 mV)	E_OV2	M_OV2	Rise:8 µs Fall:8 µs
Buck1 under- voltage (event)	N	Buck1 V <sub>OUT</sub> falling below under-voltage threshold (target voltage - V <sub>TH_PG)</sub>	E_UV1	M_UV1	0 s
Buck2 under- voltage (event)	N	Buck2 Vout falling below under-voltage threshold (target voltage - VTH_PG)	E_UV2	M_UV2	0 s

#### Table 13: Interrupt List

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-	-		-		-		



### High-Performance Dual-Channel DC-DC Converter

Name	Polarity (Note 1)	Trigger	IRQ Status Register	IRQ Mask Register	Deglitch Period
Buck1 over- current (event)	N	Buck1 current rising above over-current threshold	E_OC1	M_OC1	0 s
Buck2 over- current (event)	N	Buck2 current rising above over-current threshold	E_OC2	M_OC2	0 s
Buck1 power- good (status) (Note 2)	Р	Buck1 V <sub>OUT</sub> is in power- good voltage range (not under- or over-voltage)	PG1	M_PG1_STAT (Note 3)	0 s
Buck2 power- good (status) (Note 2)	Р	Buck2 V <sub>OUT</sub> is in power- good voltage range (not under- or over-voltage)	PG2	M_PG2_STAT (Note 3)	0 s
System good (status) (Note 2)	Р		SG	M_SG_STAT (Note 3)	0 s
Thermal warning (status) (Note 2)	N	TJ rising above Twarn	TEMP_WARN	M_VR_HOT (Note 3)	0 s
GPIO0 change (event)	N	Detect GPIO0 change for active trigger selected GPIO0_TRIG register	E_GPIO0	M_GPIO0	100 µs/
GPIO1 change (event)	N	Detect GPIO1 change for active trigger selected GPIO1_TRIG register	E_GPIO1	M_GPIO1	1 ms/ 10 ms/ 10 ms/ 100 ms
GPIO2 change (event)	N	Detect GPIO2 change for active trigger selected GPIO2_TRIG register	E_GPIO2	M_GPIO2	

**Note 1** Polarity at the source of the flag: P = active-high, N = active-low.

General rule is: normal system state is high, and abnormal system state is low (for example, PG = high means power-good, TEMP\_CRIT = low when TEMP critical state).

**Note 2** Interrupt outputs the status as is. I<sup>2</sup>C write is not required for interrupt clear.

**Note 3** OTP load value defined by CONF pin setting if CONF\_EN = 1.

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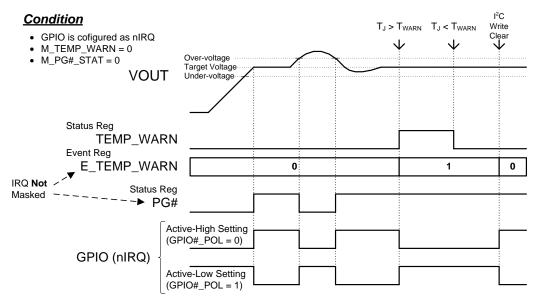
#### Table 14: Interrupt Registers Except for Power Good Status

Register	Description	
E_ <name></name>	Read-only interrupt event register	
	0: No interrupt	
	1: Interrupt occurred	
	Cleared after being written to I <sup>2</sup> C. Set until IRQ is removed.	
M_ <name></name>	Interrupt mask register	
	0: Not masked	
	1: Masked. No IRQ signal sent. Event register (E_ <name>) is updated.</name>	

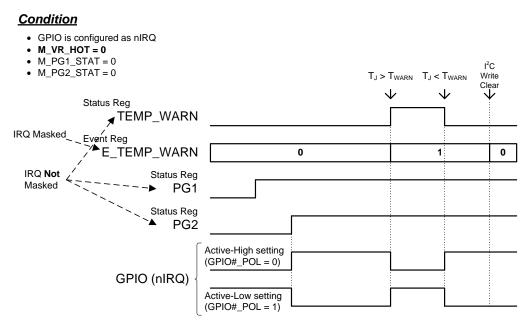
#### Table 15: Interrupt Registers for Power Good, System Good, and Temp Warning Status

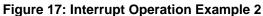
Register	Description
PG <x></x>	Buck <x> power good status. Asserted as long as the buck<x> output voltage is in range (under-voltage threshold &lt; buck output voltage &lt; over-voltage threshold) 0: Not power good 1: Power good</x></x>
M_PG <x>_STAT</x>	Power good status interrupt mask register 0: Not masked 1: Masked. No IRQ signal sent. Power good status register (PG <x>) is updated</x>
SG	System good status 0: Not system good 1: System good
M_SG_STAT	System good status (SG) interrupt mask register 0: Not masked 1: Masked. No IRQ signal sent. System good status register (SG) is updated
TEMP_WARN	Asserted as long as the thermal warning threshold (T <sub>WARN</sub> ) is reached 0: Junction temperature is below T <sub>WARN</sub> 1: Junction temperature is above T <sub>WARN</sub>
M_VR_HOT	Temperature warning status (TEMP_WARN) interrupt mask register 0: Not masked 1: Masked. No IRQ signal sent. Temperature warning status register (TEMP_WARN) is updated





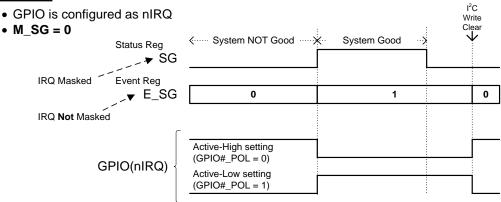








#### <u>Condition</u>





#### **Condition**

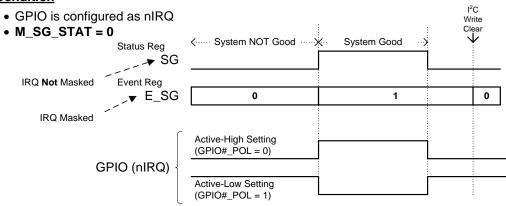


Figure 19: Interrupt Operation Example 4

#### 4.2.3 GPIO

#### 4.2.3.1 GPIO Pin Assignment

The DA9122 provides up to five GPIO pins, three if the  $l^2C$  is enabled, see Table 16. These registers are OTP programmable. When CONF\_EN = 1 GPIO0 can be used for chip configuration.

Any register settings for GPIO3 and GPIO4 are ignored and GPIO3 and GPIO4 function as SCL and SDA respectively if I2C\_EN = 1.

**Note:** GPIO3 and GPIO4 functions are limited only to output features if I2C\_EN=0.

OTP Option		GPIO Pin				Available	
I2C_EN	CONF_EN	CONF/ GPIO0	GPIO1	GPIO2	SCL/ GPIO3	SDA/ GPIO4	Available GPIOs
1'b0	1'b0	GPIO0	GPIO1	GPIO2	GPIO3	GPIO4	5
	1'b1	CONF	GPIO1	GPIO2	GPIO3	GPIO4	4
1'b1	1'b0	GPIO0	GPIO1	GPIO2	SCL	SDA	3
	1'b1	CONF	GPIO1	GPIO2	SCL	SDA	2

#### 4.2.3.2 GPIO Function

The GPIOs pins are configurable as the following functions in register GPIO<x>\_MODE (x = 0 to 4):

**Note**: When x = 3 and 4, GPIOs can be used as outputs only.

- Buck1 enable input (EN1)
- Buck2 enable input (EN2)
- Buck1 and Buck2 enable input (EN1 & EN2)
- Buck1 DVC control input (DVC1)
- Buck2 DVC control input (DVC2)
- Buck1 and Buck2 DVC control input (DVC1 & DVC2)
- Buck1 and Buck2 OTP setting reload input (RELOAD)
- Buck1 power good output (PG1)
- Buck2 power good output (PG2)
- Buck1 power good and Buck2 power good output (PG1 & PG2)
- System good output (SG)
- Interrupt output (nIRQ)

#### Table 17: GPIO Function Configuration

GPIO <x>_MODE[3:0]</x>	Function	IO Condition
4'h0	GPIO disable	HiZ
4'h1	EN1	In
4'h2	EN2	In
4'h3	EN1 & EN2	In
4'h4	DVC1	In
4'h5	DVC2	In
4'h6	DVC1 & DVC2	In

**Datasheet** 

**Revision 2.3** 



GPIO <x>_MODE[3:0]</x>	Function	IO Condition
4'h7	RELOAD	In
4'h8	PG1	Out
4'h9	PG2	Out
4'hA	PG1 & PG2	Out
4'hB	SG	Out
4'hC	nIRQ	Out
4'hD	Reserved	HiZ
4'hE	Low level	Out
4'hF	High level	Out

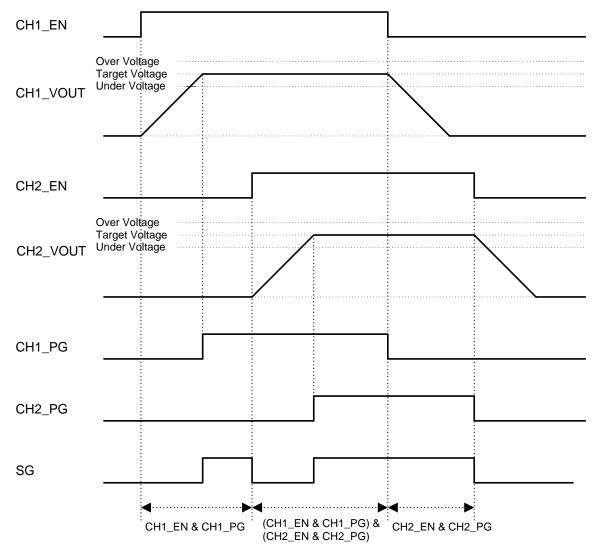


Figure 20: Power Good (PG) and System Good (SG)

#### 4.2.3.3 Chip Configuration Select (CONF)

GPIO0 functions as chip configuration select (CONF) input when CONF\_EN = 1.

Three different chip configurations can be selected according to the CONF pin level, whether it is HIGH, LOW, or Hi-Z.

#### Table 18: GPIO0-Configurable Registers when CONF\_EN = 1

Register Name	Description
IF_SLAVE_ADDR[6:0]	I2C slave address
CH1_A_MODE[1:0]	CH1_A Operation mode select
CH1_B_MODE[1:0]	CH1_B Operation mode select
CH1_VSEL	CH1 output voltage and operation selection
CH1_EN	CH1 enable
CH1_A_VOUT[7:0]	CH1 output voltage setting A
CH1_B_VOUT[7:0]	CH1 output voltage setting B
CH2_A_MODE[1:0]	CH2_A Operation mode select
CH2_B_MODE[1:0]	CH2_B Operation mode select
CH2_VSEL	CH2 output voltage and operation selection
CH2_EN	CH2 enable
CH2_A_VOUT[7:0]	CH2 output voltage setting A
CH2_B_VOUT[7:0]	CH2 output voltage setting B
M_PG1_STAT	IRQ mask setting for CH1 power good status
M_PG2_STAT	IRQ mask setting for CH2 power good status
M_SG_STAT	IRQ mask setting for system good status
M_VR_HOT	IRQ mask setting for temp warning status
CH1_EN_DLY[3:0]	Delay setting for CH1 enable
CH1_DIS_DLY[3:0]	Delay setting for CH1 disable
CH2_EN_DLY[3:0]	Delay setting for CH2 enable
CH2_DIS_DLY[3:0]	Delay setting for CH2 disable
GPIO1_MODE[3:0]	GPIO1 mode setting
GPIO2_MODE[3:0]	GPIO2 mode setting
GPIO1_OBUF	GPIO1 output buffer select
GPIO2_OBUF	GPIO2 output buffer select
GPIO1_TRIG[1:0]	GPIO1 input trigger select
GPIO1_POL	GPIO1 polarity select
GPIO1_PUPD	GPIO1 pull-up/pull-down enable
GPIO1_DEB[1:0]	GPIO1 input debounce time setting
GPIO1_DEB_RISE	GPIO1 input debounce rising edge enable
GPIO1_DEB_FALL	GPIO1 input debounce falling edge enable
GPIO2_TRIG[1:0]	GPIO2 input trigger select
GPIO2_POL	GPIO2 polarity select

#### Datasheet

#### **Revision 2.3**



### High-Performance Dual-Channel DC-DC Converter

Register Name	Description
GPIO2_PUPD	GPIO2 pull-up/pull-down enable
GPIO2_DEB[1:0]	GPIO2 input debounce time setting
GPIO2_DEB_RISE	GPIO2 input debounce rising edge enable
GPIO2_DEB_FALL	GPIO2 input debounce falling edge enable

#### 4.2.3.4 OTP Reload (RELOAD)

Buck settings listed in Table 19 are reloaded from CONF registers by triggering GPIO configured as RELOAD input.

The OTP reload happens at the same time for Buck1 and Buck2 settings. During reloading, Buck1/2 keep operating as configured without shut-down.

Register Name	Description
CH#_VSEL	CH# output voltage and operation selection. 0: A, 1: B
CH#_A_VOUT[7:0]	CH# output voltage setting A : CH#_A_VOUT * 10 mV Setting under 0.3V is clamped to 0.3V, and setting over 1.9V is clamped to 1.9 V
CH#_B_VOUT[7:0]	CH# output voltage setting B : CH#_A_VOUT * 10 mV Setting under 0.3 V is clamped to 0.3 V, and setting over 1.9V is clamped to 1.9 V
CH#_A_MODE[1:0]	Operation mode selection 0: Force PFM 1: Force PWM. full phase 2: Force PWM with phase shedding 3: Auto mode
CH#_B_MODE[1:0]	Operation mode selection 0: Force PFM 1: Force PWM. full phase 2: Force PWM with phase shedding 3: Auto mode

#### **Table 19: OTP Reload Registers**

### 4.3 **Operating Modes**

#### 4.3.1 ON

DA9122 is ON when the IC\_EN port is higher than  $V_{IH_{EN}}$  and the supply voltage is higher than  $V_{THR_{POR}}$ . Once enabled, the host processor can start communicating with DA9122 using the control interface, after the t<sub>IC\_EN</sub> delay.

#### 4.3.2 OFF

DA9122 is OFF when the IC\_EN port is lower than  $V_{IL_EN}$ . In OFF, the bucks are always disabled and LX nodes are pulled down by (typically 150  $\Omega$ ) internal pull-down resistors.

#### 4.4 I<sup>2</sup>C Communication

All features of DA9122 can be controlled with the I<sup>2</sup>C interface which is enabled or disabled in register I2C\_EN.

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### High-Performance Dual-Channel DC-DC Converter

I2C_EN	Description
0	I <sup>2</sup> C disable: SCL/GPIO3 and SDA/GPIO4 pins can be used as GPIO
1	I <sup>2</sup> C enable: SCL/GPIO3 and SDA/GPIO4 pins are used as I <sup>2</sup> C clock input and I <sup>2</sup> C data input/output.

GPIO3 functions as the l<sup>2</sup>C clock and GPIO4 carries all the power manager bidirectional l<sup>2</sup>C data. The l<sup>2</sup>C interface is open-drain supporting multiple devices on a single line. The bus lines have to be pulled high by external pull-up resistors (2 k $\Omega$  to 20 k $\Omega$ ). The standard frequency of the l<sup>2</sup>C bus is 1 MHz in fast-mode plus (FM+), 400 kHz in fast-mode, or 100 kHz in standard mode.

#### 4.4.1 I<sup>2</sup>C Protocol

All data is transmitted across the I<sup>2</sup>C bus in eight-bit groups. To send a bit, the SDA line is driven towards the intended state while the SCL is low (a low SDA indicates a zero bit). Once the SDA has settled, the SCL line is brought high and then low. This pulse on SCL clocks the SDA bit into the receiver's shift register.

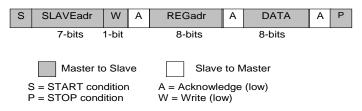
A two-byte serial protocol is used containing one byte for address and one byte data. Data and address transfer are transmitted MSB first for both read and write operations. All transmissions begin with the START condition from the master while the bus is in idle state (the bus is free). It is initiated by a high to low transition on the SDA line while the SCL is in the high state (a STOP condition is indicated by a low to high transition on the SDA line while the SCL is in the high state).



Figure 21: I<sup>2</sup>C START and STOP Condition Timing

The I<sup>2</sup>C bus is monitored for a valid slave address whenever the interface is enabled. It responds immediately when it receives its own slave address. The acknowledge is done by pulling the SDA line low during the following clock cycle (white blocks marked with A in Figure 22 and Figure 23).

The protocol for a register write from master to slave consists of a START condition, a slave address with read/write bit, and the eight-bit register address followed by eight bits of data, terminated by a STOP condition. DA9122 responds to all bytes with acknowledge (A), see Figure 22.





When the host reads data from a register it first has to write to DA9122 with the target register address and then read from DA9122 with a repeated START, or alternatively a second START, condition. After receiving the data, the host sends no acknowledge (A\*) and terminates the transmission with a STOP condition, see Figure 23.

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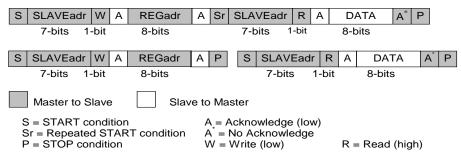


Figure 23: I<sup>2</sup>C Byte Read (SDA Line) Examples

**Datasheet** 

## High-Performance Dual-Channel DC-DC Converter

# **5 Register Definitions**

### 5.1 Register Map

#### Table 20: Register Map

Addr	Register	7	6	5	4	3	2	1	0
Systen	n Module		•						
Systen	n								
0x000 1	SYS_STATUS_0	Reserved	Reserved	Reserve d	Reserved	Reserved	Reserved SG		TEMP_WAR N
0x000 2	SYS_STATUS_1	PG2	OV2	UV2	OC2	PG1	OV1	UV1	OC1
0x000 3	SYS_STATUS_2	Reserved	Reserved	Reserve d	Reserved	Reserved	GPIO2	GPIO1	GPIO0
0x000 4	SYS_EVENT_0	Reserved	Reserved	Reserve d	Reserved	Reserved	E_SG	E_TEMP_CR IT	E_TEMP_WA RN
0x000 5	SYS_EVENT_1	E_PG2	E_OV2	E_UV2	E_OC2	E_PG1	E_OV1	E_UV1	E_OC1
0x000 6	SYS_EVENT_2	Reserved	Reserved	Reserve d	Reserved	Reserved	E_GPIO2	E_GPIO1	E_GPIO0
0x000 7	SYS_MASK_0	Reserved	Reserved	Reserve d	Reserved	Reserved	M_SG	M_TEMP_C RIT	M_TEMP_W ARN
0x000 8	SYS_MASK_1	M_PG2	M_OV2	M_UV2	M_OC2	M_PG1	M_OV1	M_UV1	M_OC1
0x000 9	SYS_MASK_2	Reserved	Reserved	Reserve d	Reserved	Reserved	M_GPIO2	M_GPIO1	M_GPIO0
0x000 A	SYS_MASK_3	Reserved	Reserved	Reserve d	Reserved	M_VR_HOT	M_SG_ST AT	M_PG2_STA T	M_PG1_STA T
0x000 B	SYS_CONFIG_0	CH1_DIS_DLY<3	CH1_DIS_DLY<3:0> CH1_EN_DLY<3:0>						
0x000 C	SYS_CONFIG_1	CH2_DIS_DLY<3	:0>			CH2_EN_DLY			
0x000 D	SYS_CONFIG_2	Reserved	OC_LATCHOFF<	1:0>	OC_DVC_MA SK	PG_DVC_MA	Reserved	Reserved	
0x000 E	SYS_CONFIG_3	Reserved	OSC_TUNE<2:0>			Reserved	Reserved	I2C_TIMEOU T	Reserved
0x001 0	SYS_GPIO0_0	Reserved	Reserved	Reserve d	GPIO0_MODE<	:3:0>			GPIO0_OBU F
0x001 1	SYS_GPIO0_1	GPIO0_DEB_F ALL	GPIO0_DEB_RI SE	GPIO0_DE	EB<1:0>	GPIO0_PU PD	GPIO0_PO L	GPIO0_TRIG<	1:0>
0x001 2	SYS_GPIO1_0	Reserved	Reserved	Reserve d	GPIO1_MODE<	:3:0>			GPIO1_OBU F
0x001 3	SYS_GPIO1_1	GPIO1_DEB_F ALL	GPIO1_DEB_RI SE	GPIO1_DE	EB<1:0>	GPIO1_PU PD	GPIO1_PO L	GPIO1_TRIG<	1:0>
0x001 4	SYS_GPIO2_0	Reserved	Reserved	Reserve d	GPIO2_MODE<	:3:0>		GPIO2_OBU F	
0x001 5	SYS_GPIO2_1	GPIO2_DEB_F ALL	GPIO2_DEB_RI SE	GPIO2_DE	EB<1:0>	GPIO2_PU PD	GPIO2_PO L	GPIO2_TRIG<	1:0>





Addr	Register	7	6	5		4		3		2		1	0
Buck (	Control							l					
Buck1													
0x002 0	BUCK_BUCK1_0	Reserved	ed CH1_SR_DVC_DWN<2:0> CH1_SR_DVC_UP<2:0>					:2:0>			CH1_EN		
0x002 1	BUCK_BUCK1_1	Reserved	CH1_SR_SHDN<	H1_SR_SHDN<2:0>				CH1_SR_STARTUP<2:0>					CH1_PD_DIS
0x002 2	BUCK_BUCK1_2	Reserved	Reserved	Reserve d	Re	served	CI	H1_ILIM<3:0:	>				
0x002 3	BUCK_BUCK1_3	CH1_VMAX<7:0>											
0x002 4	BUCK_BUCK1_4	Reserved	Reserved	Reserve d	CH	11_VSEL	CH1_B_MODE<1:0>			CH	1_A_MODE	<1:0>	
0x002 5	BUCK_BUCK1_5	CH1_A_VOUT<7	0>										
0x002 6	BUCK_BUCK1_6	CH1_B_VOUT<7	0>										
0x002 7	BUCK_BUCK1_7	Reserved	Reserved	Reser d	ve	Reserved		Reserved		Reserved		CH1_RIPPLE_CANCEL<	
Buck2													
0x002 8	BUCK_BUCK2_0	Reserved	CH2_SR_DVC_D	WN<2:0>			CI	H2_SR_DVC	UP<	:2:0>			CH2_EN
0x002 9	BUCK_BUCK2_1	Reserved	CH2_SR_SHDN<	2:0>			CH2_SR_STARTUP<2:0>					CH2_PD_DIS	
0x002 A	BUCK_BUCK2_2	Reserved	Reserved	Reserve d	Re	served	CI	H2_ILIM<3:0:	>				
0x002 B	BUCK_BUCK2_3	CH2_VMAX<7:0>											
0x002 C	BUCK_BUCK2_4	Reserved	Reserved	Reserve d	CH	12_VSEL	CH2_B_MODE<1:0>			CH2_A_MODE<1:0>		<1:0>	
0x002 D	BUCK_BUCK2_5	CH2_A_VOUT<7	0>										
0x002 E	BUCK_BUCK2_6	CH2_B_VOUT<7	0>										
0x002 F	BUCK_BUCK2_7	Reserved	Reserved	Reserved Reserve Reserved d		Reserved		Reserved	ed Reserved CH2_R 0>			E_CANCEL<1:	
Seriali	Serialization												
0x004 8	OTP_DEVICE_ID	DEV_ID<7:0>											
0x004 9	OTP_VARIANT_I D	MRC<3:0>	MRC<3:0> VRC<3:0>										
0x004 A	OTP_CUSTOME R_ID	CUST_ID<7:0>	CUST_ID<7:0>										
0x004 B	OTP_CONFIG_I D	CONFIG_REV<7:0>											

#### 5.1.1 System

#### Table 21: SYS\_STATUS\_0 (0x0001)

Bit	Symbol	Description
[2]	SG	Asserted as long as the enabled buck output voltage is in range
[1]	TEMP_CRIT	Asserted as long as the thermal shutdown threshold is reached
[0]	TEMP_WARN	Asserted as long as the thermal warning threshold is reached

#### Table 22: SYS\_STATUS\_1 (0x0002)

Bit	Symbol	Description
[7]	PG2	Asserted as long as the Buck2 output voltage is in range
[6]	OV2	Asserted as long as Buck2 hitting over-voltage
[5]	UV2	Asserted as long as Buck2 hitting under-voltage
[4]	OC2	Asserted as long as Buck2 hitting over-current
[3]	PG1	Asserted as long as the Buck1 output voltage is in range
[2]	OV1	Asserted as long as Buck1 hitting over-voltage
[1]	UV1	Asserted as long as Buck1 hitting under-voltage
[0]	OC1	Asserted as long as Buck1 hitting over-current

#### Table 23: SYS\_STATUS\_2 (0x0003)

Bit	Symbol	Description
[2]	GPIO2	GPIO2 status
[1]	GPIO1	GPIO1 status
[0]	GPIO0	GPIO0 status

#### Table 24: SYS\_EVENT\_0 (0x0004)

Bit	Symbol	Description
[2]	E_SG	SG caused event. Writing 1 action clear this bit into 0 if event source has been released.
[1]	E_TEMP_CRIT	TEMP_CRIT caused event. Writing 1 action clear this bit into 0 if event source has been released.
[0]	E_TEMP_WARN	TEMP_WARN caused event. Writing 1 action clear this bit into 0 if event source has been released.

#### Table 25: SYS\_EVENT\_1 (0x0005)

Bit	Symbol	Description
[7]	E_PG2	PG2 caused event. Writing 1 action clear this bit into 0 if event source has been released.
[6]	E_OV2	OV2 caused event. Writing 1 action clear this bit into 0 if event source has been released.
[5]	E_UV2	UV2 caused event. Writing 1 action clear this bit into 0 if event source has been released.

#### **Datasheet**

**Revision 2.3** 

Bit	Symbol	Description		
[4]	E_OC2	OC2 caused event. Writing 1 action clear this bit into 0 if event source has been released.		
[3]	E_PG1	G1 caused event. Writing 1 action clear this bit into 0 if event source has een released.		
[2]	E_OV1	OV1 caused event. Writing 1 action clear this bit into 0 if event source has been released.		
[1]	E_UV1	UV1 caused event. Writing 1 action clear this bit into 0 if event source has been released.		
[0]	E_OC1	OC1 caused event. Writing 1 action clear this bit into 0 if event source has been released.		

### Table 26: SYS\_EVENT\_2 (0x0006)

Bit	Symbol	Description		
[2]	E_GPIO2	GPIO2 event. Writing 1 action clear this bit into 0 if event source has been released.		
[1]	E_GPIO1	GPIO1 event. Writing 1 action clear this bit into 0 if event source has been released.		
[0]	E_GPIO0	GPIO0 event. Writing 1 action clear this bit into 0 if event source has been released.		

### Table 27: SYS\_MASK\_0 (0x0007)

Bit	Symbol	Description		
[2]	M_SG	SG IRQ mask		
[1]	M_TEMP_CRIT	TEMP_CRIT IRQ mask		
[0]	M_TEMP_WARN	TEMP_WARN IRQ mask		

### Table 28: SYS\_MASK\_1 (0x0008)

Bit	Symbol	Description		
[7]	M_PG2	PG2 event IRQ mask		
[6]	M_OV2	OV2 event IRQ mask		
[5]	M_UV2	UV2 event IRQ mask		
[4]	M_OC2	OC2 event IRQ mask		
[3]	M_PG1	PG1 event IRQ mask		
[2]	M_OV1	OV1 event IRQ mask		
[1]	M_UV1	UV1 event IRQ mask		
[0]	M_OC1	OC1 event IRQ mask		

### Table 29: SYS\_MASK\_2 (0x0009)

Bit	Symbol	Description		
[2]	M_GPIO2	SPIO2 IRQ mask		
[1]	M_GPIO1	GPIO1 IRQ mask		
[0]	M_GPIO0	GPIO0 IRQ mask		

**Datasheet** 

**Revision 2.3** 

### Table 30: SYS\_MASK\_3 (0x000A)

Bit	Symbol	Description		
[3]	M_VR_HOT	Temp warning status IRQ mask. Initial value is determined by CONF pin setting at the start-up in CONF_EN = $1$		
[2]	M_SG_STAT	SG status IRQ mask. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1		
[1]	M_PG2_STAT	PG2 status IRQ mask Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1		
[0]	M_PG1_STAT	PG1 status IRQ mask. Initial value is determined by CONF pin setting at the start-up in CONF_EN = $1$		

### Table 31: SYS\_CONFIG\_0 (0x000B)

Bit	Symbol	Description		
[7:4]	CH1_DIS_DLY	Delay for CH1 disable. Active with GPIO configured as EN1&EN2 control and IC_EN control. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1		
		Value Description		
		0x0	0	
		0x1	1.0 ms	
		0x2	2.0 ms	
		0x3	3.0 ms	
		0x4	4.0 ms	
		0x5	5.0 ms	
		0x6	6.0 ms	
		0x7	7.0 ms	
		0x8	8.0 ms	
		0x9	9.0 ms	
		0xA	10.0 ms	
		0xB	11.0 ms	
		0xC	12.0 ms	
		0xD	13.0 ms	
		0xE	14.0 ms	
		0xF	15.0 ms	
[3:0]	CH1_EN_DLY	Delay for CH1 enable. Active with GPIO configured as EN1&EN2 control and IC_EN control. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1		
		Value	Description	
		0x0	0	
		0x1	0.5 ms	
		0x2	1.0 ms	
		0x3	1.5 ms	

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Bit	Symbol	Description	
		0x4	2.0 ms
		0x5	2.5 ms
		0x6	3.0 ms
		0x7	3.5 ms
		0x8	4.0 ms
		0x9	4.5 ms
		0xA	5.0 ms
		0xB	5.5 ms
		0xC	6.0 ms
		0xD	6.5 ms
		0xE	7.0 ms
		0xF	7.5 ms

# Table 32: SYS\_CONFIG\_1 (0x000C)

Bit	Symbol	Description		
[7:4]	CH2_DIS_DLY	Delay for CH2 disable. Active with GPIO configured as EN1&EN2 control and IC_EN control. Initial value is determined by CONF pin setting at the start-up in CONF_EN = $1$		
		Value Description		
		0x0	0	
		0x1	1.0 ms	
		0x2	2.0 ms	
		0x3	3.0 ms	
		0x4	4.0 ms	
		0x5	5.0 ms	
		0x6	6.0 ms	
		0x7	7.0 ms	
		0x8	8.0 ms	
		0x9	9.0 ms	
		0xA	10.0 ms	
		0xB	11.0 ms	
		0xC	12.0 ms	
		0xD	13.0 ms	
		0xE	14.0 ms	
		0xF	15.0 ms	
[3:0]	CH2_EN_DLY		enable. Active with GPIO configured as EN1&EN2 control ntrol. Initial value is determined by CONF pin setting at the NF_EN = 1	

**Revision 2.3** 



Bit	Symbol	Description	
		Value	Description
		0x0	0
		0x1	0.5 ms
		0x2	1.0 ms
		0x3	1.5 ms
		0x4	2.0 ms
		0x5	2.5 ms
		0x6	3.0 ms
		0x7	3.5 ms
		0x8	4.0 ms
		0x9	4.5 ms
		0xA	5.0 ms
		0xB	5.5 ms
		0xC	6.0 ms
		0xD	6.5 ms
		0xE	7.0 ms
		0xF	7.5 ms

### Table 33: SYS\_CONFIG\_2 (0x000D)

Bit	Symbol	Description		
[6:5]	OC_LATCHOFF	Over-current latch-off setting. BUCK shut-down after OCP for 8 $\mu$ s/1 ms/3 ms unless disable setting. IRQ is generated unless IRQ is masked.		
		Value Description		
		0x0	Latch off disable	
		0x1	Latch off after 8 µs of OCP signal	
		0x2	Latch off after 1 ms of OCP signal	
		0x3	Latch off after 3 ms of OCP signal	
[4]	OC_DVC_MASK	Over-current event (IRQ and latch-off feature) mask during DVC ramp-up and ramp-down for both CH1 and CH2		
[3:2]	PG_DVC_MASK	Power-good r	mask during DVC for both CH1 and CH	
		Value	Description	
		0x0	No mask	
		0x1 Mask as not power good during DVC		
		0x2	Mask as power good during DVC	
		0x3	Reserved	

Datasheet

**Revision 2.3** 

Bit	Symbol	Description		
[6:4]	OSC_TUNE	Tune oscillator frequency, tuned frequency = Current + OSC_TUNE * 160 kHz		
		Value Description		
		0x3	3	
		0x2	2	
		0x1 1		
		0x0	0	
		0x7	-1	
		0x6	-2	
		0x5	-3	
		0x4	-4	
[1]	I2C_TIMEOUT	Enable automatic reset of 2-wire interface (if SDA stays low for >50 ms).		

### Table 34: SYS\_CONFIG\_3 (0x000E)

### Table 35: SYS\_GPIO0\_0 (0x0010)

Bit	Symbol	Description	
[4:1]	GPIO0_MODE	GPIO function	on mode select
		Value	Description
		0x0	GPIO disable
		0x1	EN1 input
		0x2	EN2 input
		0x3	EN1 & EN2 input
		0x4	DVC1 input
		0x5	DVC2 input
		0x6	DVC1 & DVC2 input
		0x7	RELOAD input
		0x8	PG1 output
		0x9	PG2 output
		0xA	PG1 & PG2 output
		0xB	SG output
		0xC	nIRQ output
		0xD	Reserved
		0xE	Low output
		0xF	High output
[0]	GPIO0_OBUF	GPIO output	t buffer select
		Value	Description
		0x0	open-drain output

#### Datasheet

# DA9122



## High-Performance Dual-Channel DC-DC Converter

Bit	Symbol	Description	
		0x1	push-pull output

### Table 36: SYS\_GPIO0\_1 (0x0011)

Bit	Symbol	Description	
[7]	GPIO0_DEB_FALL	GPI debouc	e falling edge
[6]	GPIO0_DEB_RISE	GPI debounce rising edge	
[5:4]	GPIO0_DEB	GPI debounce time	
		Value	Description
		0x0	100 µs debouce
		0x1	1 ms debouce
		0x2	10 ms debounce
		0x3	100 ms debounce
[3]	GPIO0_PUPD	GPIO pull-up	o/pull-down enable
		Value	Description
		0x0	GPI: pull-down disabled, GPO: pull-up to AVDD disabled
		0x1	GPI: pull-down enabled, GPO: pull-up to AVDD enabled
[2]	GPIO0_POL	GPIO polarit	у
		Value	Description
		0x0	GPIO is active-high
		0x1	GPIO is active-low
[1:0]	GPIO0_TRIG	GPI trigger t	уре
		Value	Description
		0x0	Dual-edge triggered
		0x1	Pos-edge triggered
		0x2	Neg-edge triggered
		0x3	Reserved (No trigger)

### Table 37: SYS\_GPIO1\_0 (0x0012)

Bit	Symbol	Description	
[4:1]	GPIO1_MODE	GPIO function mode select. Initial value is determined by CONF pi setting at the start-up in CONF_EN = 1	
		Value	Description
		0x0	GPIO disable
		0x1	EN1 input
		0x2	EN2 input
		0x3	EN1 & EN2 input
		0x4	DVC1 input

#### Datasheet

**Revision 2.3** 



Bit	Symbol	Description	
		0x5	DVC2 input
		0x6	DVC1 & DVC2 input
		0x7	RELOAD input
		0x8	PG1 output
		0x9	PG2 output
		0xA	PG1 & PG2 output
		0xB	SG output
		0xC	nIRQ output
		0xD	Reserved
		0xE	Low output
		0xF	High output
[0]	GPIO1_OBUF	GPIO output buffer select. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	
		Value	Description
		0x0	open-drain output
		0x1	push-pull output

### Table 38: SYS\_GPIO1\_1 (0x0013)

Bit	Symbol	Descripti	on	
[7]	GPIO1_DEB_FALL		GPI debouce falling edge. Initial value is determined by CONF pin setting at the start-up in $CONF_EN = 1$	
[6]	GPIO1_DEB_RISE		GPI debounce rising edge. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	
[5:4]	GPIO1_DEB		unce time. Initial value is determined by CONF pin setting t-up in CONF_EN = 1	
		Value	Description	
		0x0	100 µs debouce	
		0x1	1 ms debouce	
		0x2	10 ms debounce	
		0x3	100 ms debounce	
[3]	GPIO1_PUPD		-up/pull-down enable. Initial value is determined by CONF at the start-up in CONF_EN = 1	
		Value	Description	
		0x0	GPI: pull-down disabled, GPO: pull-up to AVDD disabled	
		0x1	GPI: pull-down enabled, GPO: pull-up to AVDD enabled	
[2]	GPIO1_POL		arity. Initial value is determined by CONF pin setting at the CONF_EN = 1	
		Value	Description	
		0x0	GPIO is active-high	

Revision 2.3



# DA9122

## High-Performance Dual-Channel DC-DC Converter

Bit	Symbol	Description	
		0x1	GPIO is active-low
[1:0]	GPIO1_TRIG		ype. Initial value is determined by CONF pin setting at in CONF_EN = 1
		Value	Description
		0x0	Dual-edge triggered
		0x1	Pos-edge triggered
		0x2	Neg-edge triggered
		0x3	Reserved (No trigger)

### Table 39: SYS\_GPIO2\_0 (0x0014)

Bit	Symbol	Description	Description		
[4:1]	GPIO2_MODE		on mode select. Initial value is determined by CONF pin e start-up in CONF_EN = 1		
		Value	Description		
		0x0	GPIO disable		
		0x1	EN1 input		
		0x2	EN2 input		
		0x3	EN1 & EN2 input		
		0x4	DVC1 input		
		0x5	DVC2 input		
		0x6	DVC1 & DVC2 input		
		0x7	RELOAD input		
		0x8	PG1 output		
		0x9	PG2 output		
		0xA	PG1 & PG2 output		
		0xB	SG output		
		0xC	nIRQ output		
		0xD	Reserved		
		0xE	Low output		
		0xF	High output		
[0]	GPIO2_OBUF		t buffer select. Initial value is determined by CONF pin e start-up in CONF_EN = 1		
		Value	Description		
		0x0	open-drain output		
		0x1	push-pull output		

### Table 40: SYS\_GPIO2\_1 (0x0015)

Bit	Symbol	Descripti	Description		
[7]	GPIO2_DEB_FALL		GPI debouce falling edge. Initial value is determined by CONF pin setting at the start-up in $CONF_EN = 1$		
[6]	GPIO2_DEB_RISE		GPI debounce rising edge. Initial value is determined by CONF pin setting at the start-up in CONF_EN = $1$		
[5:4]	GPIO2_DEB		unce time. Initial value is determined by CONF pin setting rt-up in CONF_EN = 1		
		Value	Description		
		0x0	100 μs debouce		
		0x1	1 ms debouce		
		0x2	10 ms debounce		
		0x3	100 ms debounce		
[3]	GPIO2_PUPD		-up/pull-down enable. Initial value is determined by CONF g at the start-up in CONF_EN = 1		
		Value	Description		
		0x0	GPI: pull-down disabled, GPO: pull-up to AVDD disabled		
		0x1	GPI: pull-down enabled, GPO: pull-up to AVDD enabled		
[2]	GPIO2_POL		arity. Initial value is determined by CONF pin setting at the CONF_EN = 1		
		Value	Description		
		0x0	GPIO is active-high		
		0x1	GPIO is active-low		
[1:0]	GPIO2_TRIG		er type. Initial value is determined by CONF pin setting at up in CONF_EN = 1		
		Value	Description		
		0x0	Dual-edge triggered		
		0x1	Pos-edge triggered		
		0x2	Neg-edge triggered		
		0x3	Reserved (No trigger)		



### 5.1.2 Buck1

### Table 41: BUCK\_BUCK1\_0 (0x0020)

Bit	Symbol	Description	
[6:4]	CH1_SR_DVC_DWN	Voltage slew	v-rate for DVC ramp-down
		Value	Description
		0x0	10 mV/8 μs
		0x1	10 mV/4 μs
		0x2	10 mV/2 μs
		0x3	10 mV/µs
		0x4	<b>20 mV/</b> µs
		0x5	Reserved
		0x6	Reserved
		0x7	Reserved
[3:1]	CH1_SR_DVC_UP	Voltage slew	v-rate for DVC ramp-up
		Value	Description
		0x0	10 mV/8 μs
		0x1	10 mV/4 μs
		0x2	10 mV/2 μs
		0x3	10 mV/µs
		0x4	20 mV/µs
		0x5	40 mV/µs
		0x6	Reserved
		0x7	Reserved
[0]	CH1_EN	Channel enable. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	

### Table 42: BUCK\_BUCK1\_1 (0x0021)

Bit	Symbol	Description	
[6:4]	CH1_SR_SHDN	Voltage slew	v-rate during shut-down
		Value	Description
		0x0	10 mV/8 μs
		0x1	10 mV/4 μs
		0x2	10 mV/2 μs
		0x3	10 mV/µs
		0x4	20 mV/µs
		0x5	Reserved
		0x6	Reserved
		0x7	Immediate power-down

**Datasheet** 





Bit	Symbol	Description		
[3:1]	CH1_SR_STARTUP	Voltage slew-rate during startup		
		Value	Description	
		0x0	10 mV/8 μs	
		0x1	10 mV/4 µs	
		0x2	10 mV/2 μs	
		0x3	10 mV/µs	
		0x4	20 mV/µs	
		0x5	40 mV/µs	
		0x6	Reserved	
		0x7	Reserved	
[0]	CH1_PD_DIS	Pull-down while buck is disabled. 0: enable, 1: disable		

### Table 43: BUCK\_BUCK1\_2 (0x0022)

Bit	Symbol	Descripti	Description		
[3:0]	CH1_ILIM	Select OC	P threshold (A)		
		Value	Description		
		0x0	Reserved		
		0x1	3.5		
		0x2	4.0		
		0x3	4.5		
		0x4	5.0		
		0x5	5.5		
		0x6	6.0		
		0x7	6.5		
		0x8	7.0		
		0x9	7.5		
		0xA	8.0		
		0xB	8.5		
		0xC	9.0		
		0xD	9.5		
		0xE	10.0		
		0xF	Disable		

## Table 44: BUCK\_BUCK1\_3 (0x0023)

Bit	Symbol	Description
[7:0]	CH1_VMAX	VOUT max setting (V): From 0.30 V (0x1E) to 1.90 V (0xBE) in 10 mV steps. This is a read-only register.

**Datasheet** 

**Revision 2.3** 



Bit	Symbol	Description		
		Value	Description	
		0x1E	0.3	
		0x1F	0.31	
		0x20	0.32	
		Continuing t	hrough	
		0x99	1.53	
		То		
		0xBD	1.89	
		0xBE	1.9	

### Table 45: BUCK\_BUCK1\_4 (0x0024)

Bit	Symbol	Description	l
[4]	CH1_VSEL	Output voltage and operation selection: 0: A, 1: B. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	
[3:2]	CH1_B_MODE	Operation mode selection. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	
		Value	Description
		0x0	Force PFM operation
		0x1	Force PWM operation
		0x2	Force PWM operation
		0x3	Auto mode
[1:0]	CH1_A_MODE	Operation mode selection. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	
		Value	Description
		0x0	Force PFM operation
		0x1	Force PWM operation
		0x2	Force PWM operation
		0x3	Auto mode

### Table 46: BUCK\_BUCK1\_5 (0x0025)

Bit	Symbol	Description	
[7:0]	CH1_A_VOUT	Output voltage setting A: Initial value is determined by CON setting at the start-up in CONF_EN = 1 From 0.30 V (0x1E) to 1.90 V (0xBE) in steps of 10 mV (de 1.0 V) Write-protected when value is written below 0.30 V or above	
		Value Description	
		0x1E 0.3	
		0x1F	0.31

```
Datasheet
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Bit	Symbol	Description	
		0x20	0.32
		Continuing t	hrough
		0x64	1
		То	
		0xBC	1.88
		0xBD	1.89
		0xBE	1.9

### Table 47: BUCK\_BUCK1\_6 (0x0026)

Bit	Symbol	Description	
[7:0]	CH1_B_VOUT	Output voltage setting B: Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1 From 0.30 V (0x1E) to 1.90 V (0xBE) in steps of 10 mV (default 1.0 V) Write-protected when value is written below 0.30 V or above 1.90	
		Value	Description
		0x1E	0.3
		0x1F	0.31
		0x20	0.32
		Continuing t	hrough
		0x64	1
		То	
		0xBC	1.88
		0xBD	1.89
		0xBE	1.9

### Table 48: BUCK\_BUCK1\_7 (0x0027)

Bit	Symbol	Description	
[1:0]	CH1_RIPPLE_CANCEL	Ripple cancel control (can be used to improve output overshoot at heavy to light load transient).	
		Value Description	
		0x0	No ripple cancel
		0x1	Small ripple cancel
		0x2	Mid ripple cancel
		0x3	Large ripple cancel

# DA9122



# High-Performance Dual-Channel DC-DC Converter

### 5.1.3 Buck2

### Table 49: BUCK\_BUCK2\_0 (0x0028)

Bit	Symbol	Description	Description		
[6:4]	CH2_SR_DVC_DWN	Voltage slew	v-rate for DVC ramp-down		
		Value	Description		
		0x0	10 mV/8 μs		
		0x1	10 mV/4 μs		
		0x2	10 mV/2 μs		
		0x3	10 mV/µs		
		0x4	20 mV/µs		
		0x5	Reserved		
		0x6	Reserved		
		0x7	Reserved		
[3:1]	CH2_SR_DVC_UP	Voltage slew	v-rate for DVC ramp-up		
		Value	Description		
		0x0	10 mV/8 μs		
		0x1	10 mV/4 μs		
		0x2	10 mV/2 μs		
		0x3	10 mV/µs		
		0x4	20 mV/µs		
		0x5	40 mV/µs		
		0x6	Reserved		
		0x7	Reserved		
[0]	CH2_EN	Channel enable. Initial value is determined by CONF pin setting at the start-up in CONF_EN = $1$			

### Table 50: BUCK\_BUCK2\_1 (0x0029)

Bit	Symbol	Description		
[6:4]	CH2_SR_SHDN	Voltage slew	v-rate during power-down	
		Value	Description	
		0x0	10 mV/8 μs	
		0x1	10 mV/4 μs	
		0x2	10 mV/2 μs	
		0x3	10 mV/µs	
		0x4	20 mV/µs	
		0x5	Reserved	
		0x6	Reserved	
		0x7	Immediate power-down	

#### Datasheet

#### **Revision 2.3**





Bit	Symbol	Description	
[3:1]	CH2_SR_STARTUP	Voltage slew	v-rate during startup
		Value	Description
		0x0	10 mV/8 µs
		0x1	10 mV/4 µs
		0x2	10 mV/2 μs
		0x3	10 mV/µs
		0x4	20 mV/µs
		0x5	40 mV/µs
		0x6	Reserved
		0x7	Reserved
[0]	CH2_PD_DIS	Pull-down while BUCK is disabled. 0: enable, 1: disable	

### Table 51: BUCK\_BUCK2\_2 (0x002A)

Bit	Symbol	Description	
[3:0]	CH2_ILIM	Select OCP	threshold
		Value	Description
		0x0	Reserved
		0x1	3.5
		0x2	4.0
		0x3	4.5
		0x4	5.0
		0x5	5.5
		0x6	6.0
		0x7	6.5
		0x8	7.0
		0x9	7.5
		0xA	8.0
		0xB	8.5
		0xC	9.0
		0xD	9.5
		0xE	10.0
		0xF	Disable

### Table 52: BUCK\_BUCK2\_3 (0x002B)

Bit	Symbol	Description
[7:0]	CH2_VMAX	VOUT max setting (V): From 0.30 V (0x1E) to 1.90 V (0xBE) in steps of 10 mV This is a read-only register.

**Revision 2.3** 



Bit	Symbol	Description	
		Value	Description
		0x1E	0.3
		0x1F	0.31
		0x20	0.32
		Continuing t	hrough
		0x64	1
		То	
		0xBC	1.88
		0xBD	1.89
		0xBE	1.9

### Table 53: BUCK\_BUCK2\_4 (0x002C)

Bit	Symbol	Description	
[4]	CH2_VSEL	Output voltage and operation selection: 0: A, 1: B. Initial value is determined by CONF pin setting at the start-up in $CONF_EN = 1$	
[3:2]	CH2_B_MODE	Operation mode selection. Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1	
		Value	Description
		0x0	Force PFM operation
		0x1	Force PWM operation
		0x2	Force PWM operation
		0x3	Auto mode
[1:0]	CH2_A_MODE		ode selection. Initial value is determined by CONF pin e start-up in CONF_EN = 1
		Value	Description
		0x0	Force PFM operation
		0x1	Force PWM operation
		0x2	Force PWM operation
		0x3	Auto mode

### Table 54: BUCK\_BUCK2\_5 (0x002D)

Bit	Symbol	Descripti	Description	
[7:0]	CH2_A_VOUT	setting at From 0.30 1.0 V)	Output voltage setting A: Initial value is determined by CONF pin setting at the start-up in CONF_EN = 1 From 0.30 V (0x1E) to 1.90 V (0xBE) in steps of 10 mV (default 1.0 V) Write-protected when value is written below 0.30 V or above 1.90	
		Value	Value Description	
		0x1E	0.3	
		0x1F	0.31	
		0x20	0.32	

Datasheet

**Revision 2.3** 





Bit	Symbol	Description	
		Continuing through	
		0x64	1
		То	
		0xBC	1.88
		0xBD	1.89
		0xBE	1.9

### Table 55: BUCK\_BUCK2\_6 (0x002E)

Bit	Symbol	Description	
[7:0]	CH2_B_VOUT	Output voltage setting B: Initial value is determined by CONF pir setting at the start-up in CONF_EN = 1 From 0.30 V (0x1E) to 1.90 V (0xBE) in steps of 10 mV (default 1.0 V) Write-protected when value is written below 0.30 V or above 1.90	
		Value	Description
		0x1E	0.3
		0x1F	0.31
		0x20	0.32
		Continuing t	hrough
		0x64	1
		То	
		0xBC	1.88
		0xBD	1.89
		0xBE	1.9

### Table 56: BUCK\_BUCK2\_7 (0x002F)

Bit	Symbol	Description	
[1:0]	CH2_RIPPLE_CANCEL	Ripple cancel control (can be used to improve output overshoot at heavy to light load transient).	
		Value	Description
		0x0	No ripple cancel
		0x1	Small ripple cancel
		0x2	Mid ripple cancel
		0x3	Large ripple cancel





### 5.1.4 Serialization

### Table 57: OTP\_DEVICE\_ID (0x0048)

Bit	Symbol	Description
[7:0]	DEV_ID	Device ID

### Table 58: OTP\_VARIANT\_ID (0x0049)

Bit	Symbol	Description
[7:4]	MRC	Mask Revision Code
[3:0]	VRC	Chip Variant Code

#### Table 59: OTP\_CUSTOMER\_ID (0x004A)

Bit	Symbol	Description
[7:0]	CUST_ID	Customer ID

### Table 60: OTP\_CONFIG\_ID (0x004B)

Bit	Symbol	Description
[7:0]	CONFIG_REV	OTP Variant

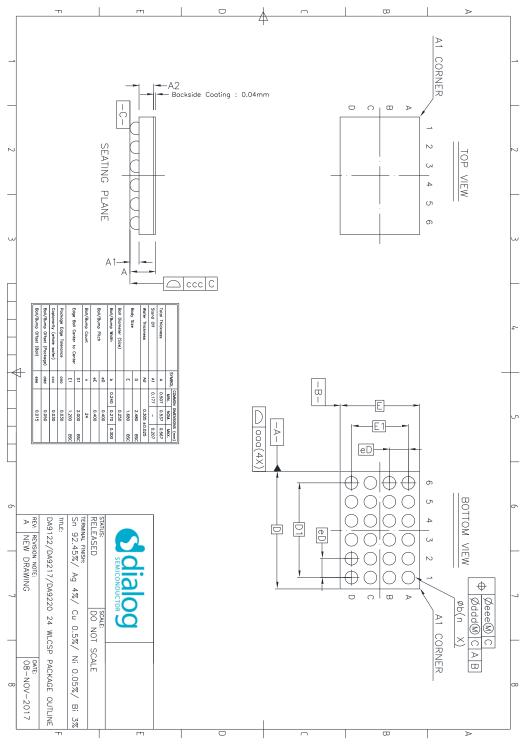
## **DA9122**



## High-Performance Dual-Channel DC-DC Converter

# 6 Package Information

### 6.1 Package Outlines





**Datasheet** 

### 6.2 Moisture Sensitivity Level

The moisture sensitivity level (MSL) is an indicator for the maximum allowable time period (floor lifetime) in which a moisture sensitive plastic device, once removed from the dry bag, can be exposed to an environment with a specified maximum temperature and a maximum relative humidity before the solder reflow process. The MSL classification is defined in Table 61.

For detailed information on MSL levels refer to the IPC/JEDEC standard J-STD-020, which can be downloaded from http://www.jedec.org.

The DA9122 package is qualified for MSL1.

#### Table 61: MSL Classification

MSL Level	Floor Lifetime	Conditions
MSL 1	Unlimited	≤30 °C / 85 % RH

### 6.3 WLCSP Handling

Manual handling of WLCSP packages should be reduced to the absolute minimum. In cases where it is still necessary, a vacuum pick-up tool should be used. In extreme cases plastic tweezers could be used, but metal tweezers are not acceptable, since contact may easily damage the silicon chip.

Removal of a WLCSP package will cause damage to the solder balls. Therefore a removed sample cannot be reused.

WLCSP packages are sensitive to visible and infrared light. Precautions should be taken to properly shield the chip in the final product.

### 6.4 Soldering Information

Refer to the IPC/JEDEC standard J-STD-020 for relevant soldering information. This document can be downloaded from http://www.jedec.org.

# 7 Ordering Information

The ordering number consists of the part number followed by a suffix indicating the packing method. For details and availability, please consult Renesas Electronics' customer support portal or your local sales representative.

### **Table 62: Ordering Information**

Part Number	Package	Size (mm)	Shipment Form	Pack Quantity
DA9122-xxV72	24 WLCSP	2.48 x 1.68	T&R	4500
DA9122-xxV76	24 WLCSP	2.48 x 1.68	Waffle Tray	140
DA9122-E0V72 Standard OTP Variant V <sub>OUT1</sub> = 1.2 V, V <sub>OUT2</sub> = 1.8 V	24 WLCSP	2.48 x 1.68	T&R	4500
DA9122-E0V76 Standard OTP Variant V <sub>OUT1</sub> = 1.2 V, V <sub>OUT2</sub> = 1.8 V	24 WLCSP	2.48 x 1.68	Waffle Tray	140
DA9122-E1V72 Standard OTP Variant V <sub>OUT1</sub> = 1.0 V, V <sub>OUT2</sub> = 1.0 V	24 WLCSP	2.48 x 1.68	T&R	4500
DA9122-E1V76 Standard OTP Variant V <sub>OUT1</sub> = 1.0 V, V <sub>OUT2</sub> = 1.0 V	24 WLCSP	2.48 x 1.68	Waffle Tray	140

# 8 Application Information

The following recommended components are examples selected from requirements of a typical application.

## 8.1 Capacitor Selection

Ceramic capacitors are used as bypass capacitors at all VDD and output rails. When selecting a capacitor, especially for types with high capacitance at smallest physical dimension, the DC bias characteristic has to be taken into account.

**Table 63: Recommended Capacitor Types** 

Application	Value	Size	Temp. Char.	Tol. (%)	V-Rate	Туре
VOUT output bypass	10 µF	0402	X5R ±15 %	±20	6.3 V	Murata GRM155R60J106ME15
PVDDx bypass	10 µF	0603	X5R ±15 %	±20	25 V	Murata GRM188R61E106MA73
AVDD bypass	1 µF	0402	X5R ±15 %	±10	10 V	Murata GRM155R61A105KE15

### 8.2 Inductor Selection

Inductors should be selected based on the following parameters:

• Rated maximum current

Usually a coil provides two current limits: ISAT specifies the maximum current at which the inductance drops by 30 % of the nominal value, and IMAX is defined by the maximum power dissipation and is applied to the effective current.

• DC resistance

Critical for the converter efficiency and should therefore be minimized.

Table 64:	Recommended	Inductor	Types
-----------	-------------	----------	-------

Value (µH)	Size (mm)	I <sub>MAX</sub> (DC) (A)	Isat <b>(A)</b>	Tol. (%)	DC Resistance (mΩ)	Туре
0.1	2.0 x 1.6 x 1.0	6.5	9.0	±20	11.5	Cyntec HTEN20161T-R10MDR
0.1	1.6 x 0.8 x 1.0	5.2	6.5	±20	17	Taiyo Yuden MEKK1608TR10M
0.1	1.6 x 0.8 x 0.8	4.1	9.4	±20	19	Taiyo Yuden MCHK1608TR10MJN
0.11	2.0 x 1.25 x 0.8	5.8	6.9	±20	9.1	Taiyo Yuden MCHK2012TR11MKG
0.1	2.5 x 2.0 x 1.2	12	13	±20	4	TDK TFM252012ALMAR10MT
0.1	1.6 x 0.8 x 0.95	3.8	4.3	±20	15	Tokyo Coil Engineering TFP160810M-R10N
0.11	2.0 x 1.6 x 0.6	3.0	6.0	±20	24	Wurth Elektronik WE-PMMI 744 799 771 11

#### **Status Definitions**

Revision	Datasheet Status	Product Status	Definition
1. <n></n>	Target	Development	This datasheet contains the design specifications for product development. Specifications may be changed in any manner without notice.
2. <n></n>	Preliminary	Qualification	This datasheet contains the specifications and preliminary characterization data for products in pre-production. Specifications may be changed at any time without notice in order to improve the design.
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**Revision 2.3**